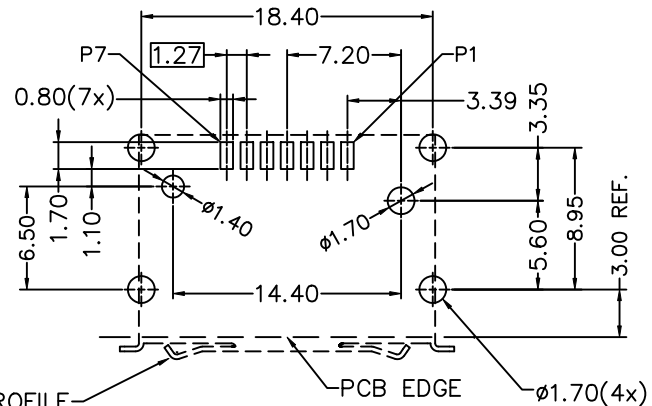
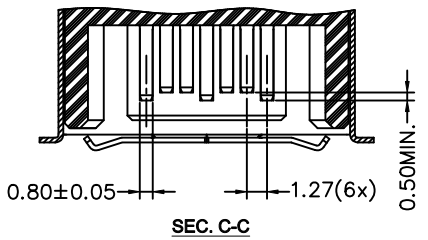
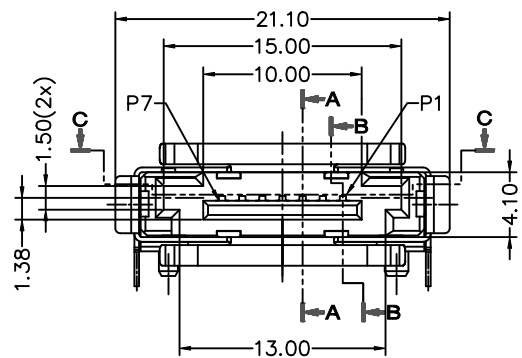
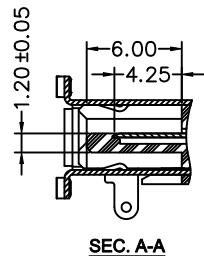
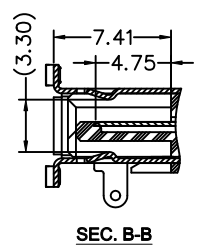


- NOTES:
- MATERIAL: HOUSING: HIGH TEMP PLASTIC WITH 30 % G/F UL94 V-0  
COLOR: BLACK  
CONTACT: COPPER ALLOY, T=0.25mm  
SHELL: COPPER ALLOY, T=0.30mm
  - FINISH:  
CONTACT: GOLD PLATING ON CONTACT AREA 100u" MIN. MATTE TIN  
PLATING ON SOLDER TAILS 50u" MIN. NICKEL UNDERPLATING OVER ALL  
SHELL: BRIGHT TIN PLATING 100u" MIN.  
50u" MIN. NICKEL UNDERPLATING OVER ALL
  - PRODUCT SPEC: GS-12-402  
PACKING SPEC: GS-14-1109
  - THE HOUSING WILL WITHSTAND EXPOSURE TO 260C PEAK TEMP FOR 10 SEC. IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
  - PRODUCT NUMBERING:  
10105449 - 00 X X LF  
LEAD FREE  
R: T&R PACKING  
1. 15U" GOLD AT CONTACT



RECOMMENDED PCB LAYOUT  
TOLERANCE: ±0.05



mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	FCI www.fciconnect.com	
ltr	ecn no	dr	date	linear	.X ± 0.38	projection	title	
A	T09-1147	S.LIN	11/17/09	angles	.XX ± 0.25	MM	E-SATA PLUG R/A TOP MOUNT SMT TYPE	
					.XXX ± 0.15		scale	product family
				dr	STERLING LIN 11/17/09	NA	SATA	TWN
				enrg	STERLING LIN 11/17/09		size	sheet
				chr	GARY HSIEH 11/17/09		dwg no	1 of 1
				appd	JOSEPH HSIA 11/17/09		10105449	
sheet index	revision sheet	A	1					